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> JP02111883A2: ELECTROLESS METAL PLATING METHOD § Title:

Electroless metal plating for high density coating - involves adsorbing PDerwent Title:

reducing agent on substrate, dipping in soln. contg. catalytic metal ions.

etc. [Derwent Record]

^② Country: JP Japan

ঔKind:

Α

§ Inventor: **MATSUI TOSHIKI:**

IMAI TOMOYUKI:

FUKUKAITO MASAAKI;

HORIISHI NANAO:

3 Assignee: **TODA KOGYO CORP**

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*Published / Filed: 1990-04-24 / 1988-10-20

> Application Number:

JP1988000265711

Advanced: C23C 18/28; C23C 18/36;

Core: C23C 18/20; C23C 18/31;

IPC-7: C23C 18/28;

C23C 18/36;

Priority Number: 1988-10-20 JP1988000265711

> PURPOSE: To form a uniform dense metal plating film having Abstract:

satisfactory adhesion without using a noble metal catalyst by adsorbing a reducing agent on a body to be plated, immersing the body in a soln. contg. ions of a self-catalytic metal, reducing the

deposited metal and carrying out electroless plating.

CONSTITUTION: A reducing agent such as an aq. soln. of sodium borohydride is adsorbed on a body to be plated. This body is immersed in an aq. soln. contg. ions of a self-catalytic metal such as Ni, Co or Cu to deposit the metal and the deposited metal is reduced with the reducing agent. The body to be plated is then electroless-plated with a metal such as Ni, Co or Cu. A uniform dense plating film having superior adhesion can be formed without

using an expensive noble metal catalyst. COPYRIGHT: (C)1990, JPO& Japio

Family: None

Other Abstract DERABS C90-169179 DERC90-169179

Info:

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